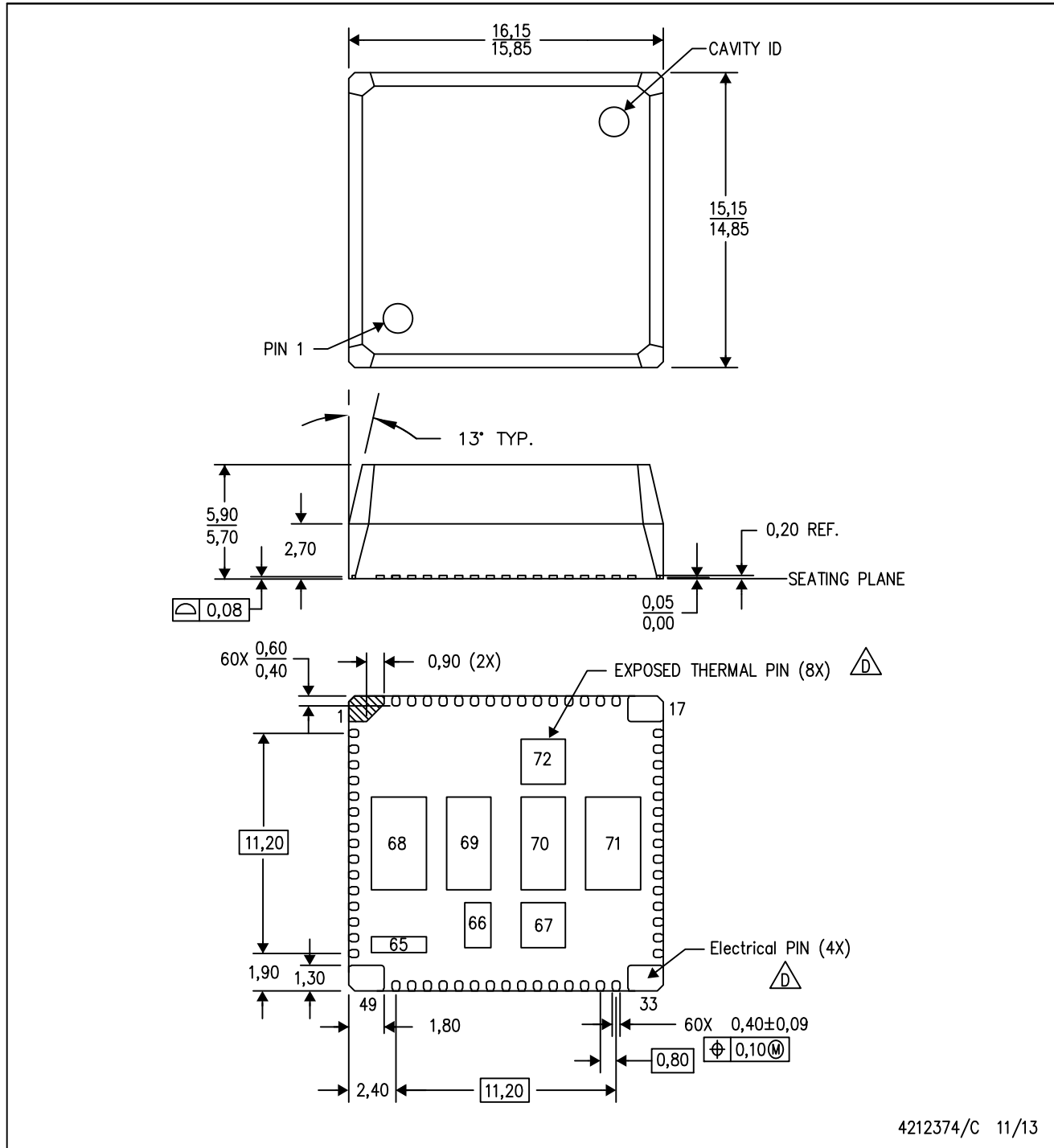




RLG (R-PB4QFN-N72)

PLASTIC QUAD FLATPACK NO-LEAD



4212374/C 11/13

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Quad Flatpack, No-leads (QFN) package configuration.
  -  The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  -  The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane..

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